Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.033”**

**.033”**

**ANODE**

**.019”**

**.019”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .019 X .019” min.**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .033” X .033” DATE: 11/4/21**

**MFG: MICROSEMI THICKNESS .009” P/N: 1N4944**

**DG 10.1.2**

#### Rev B, 7/1